



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

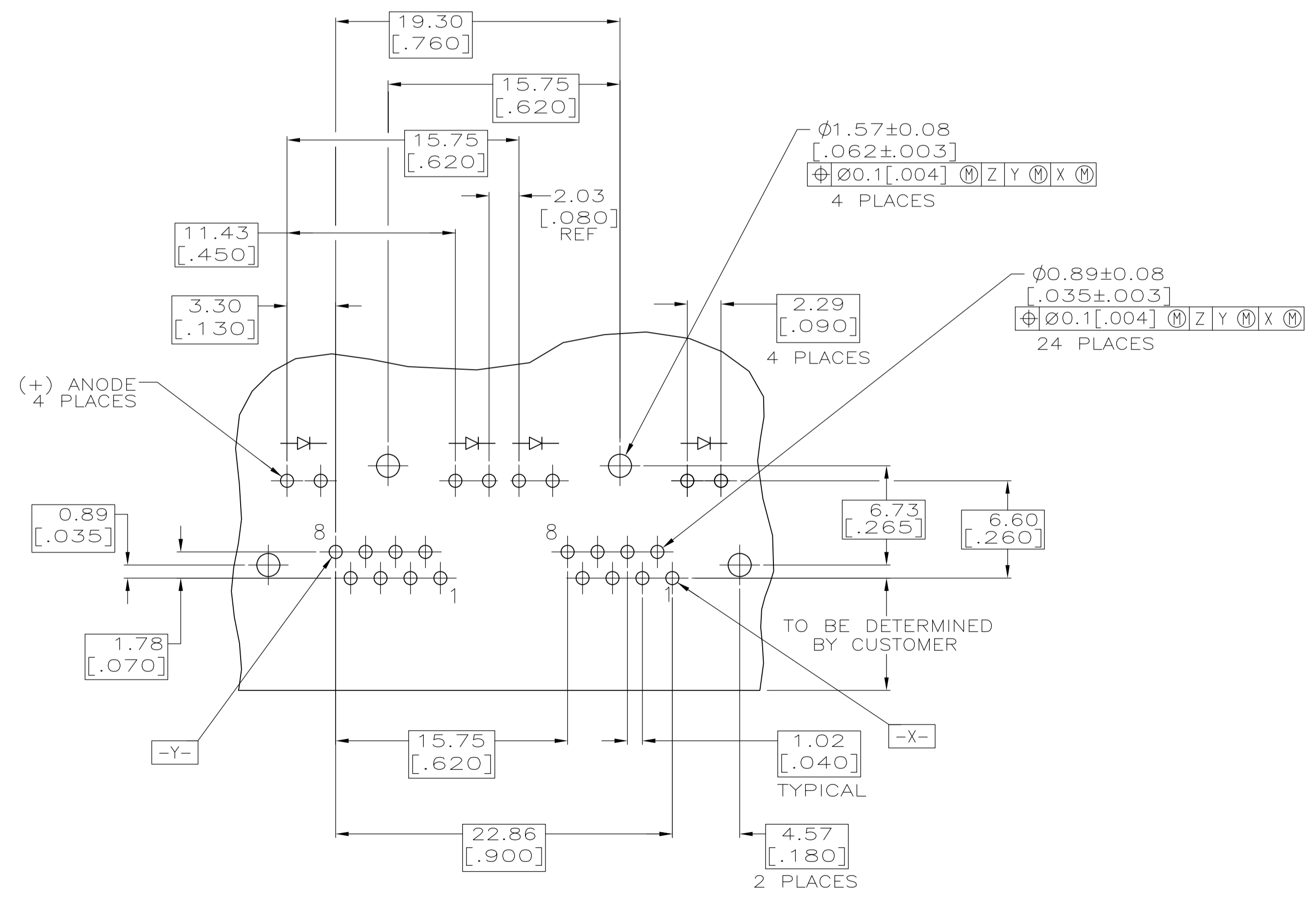
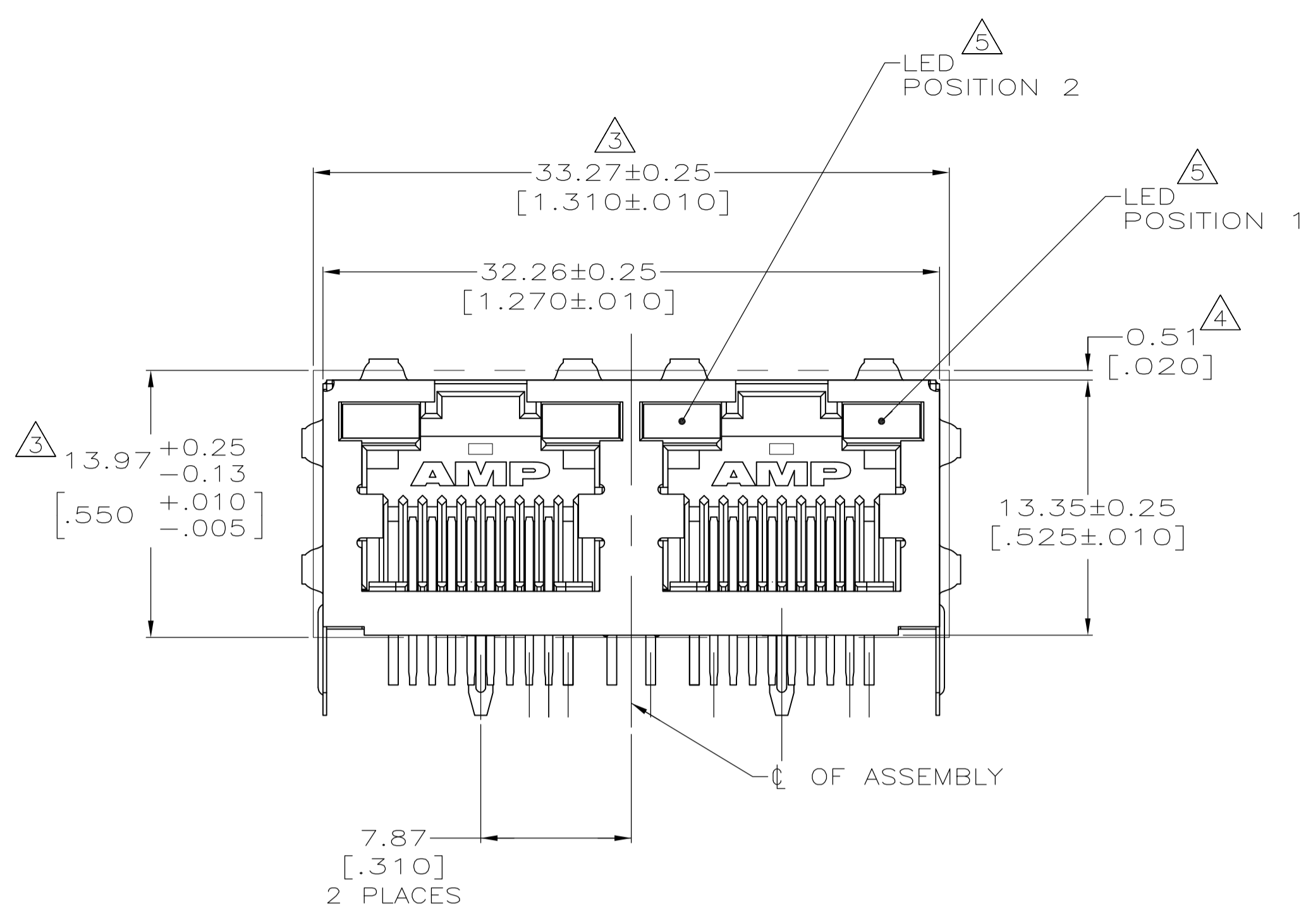
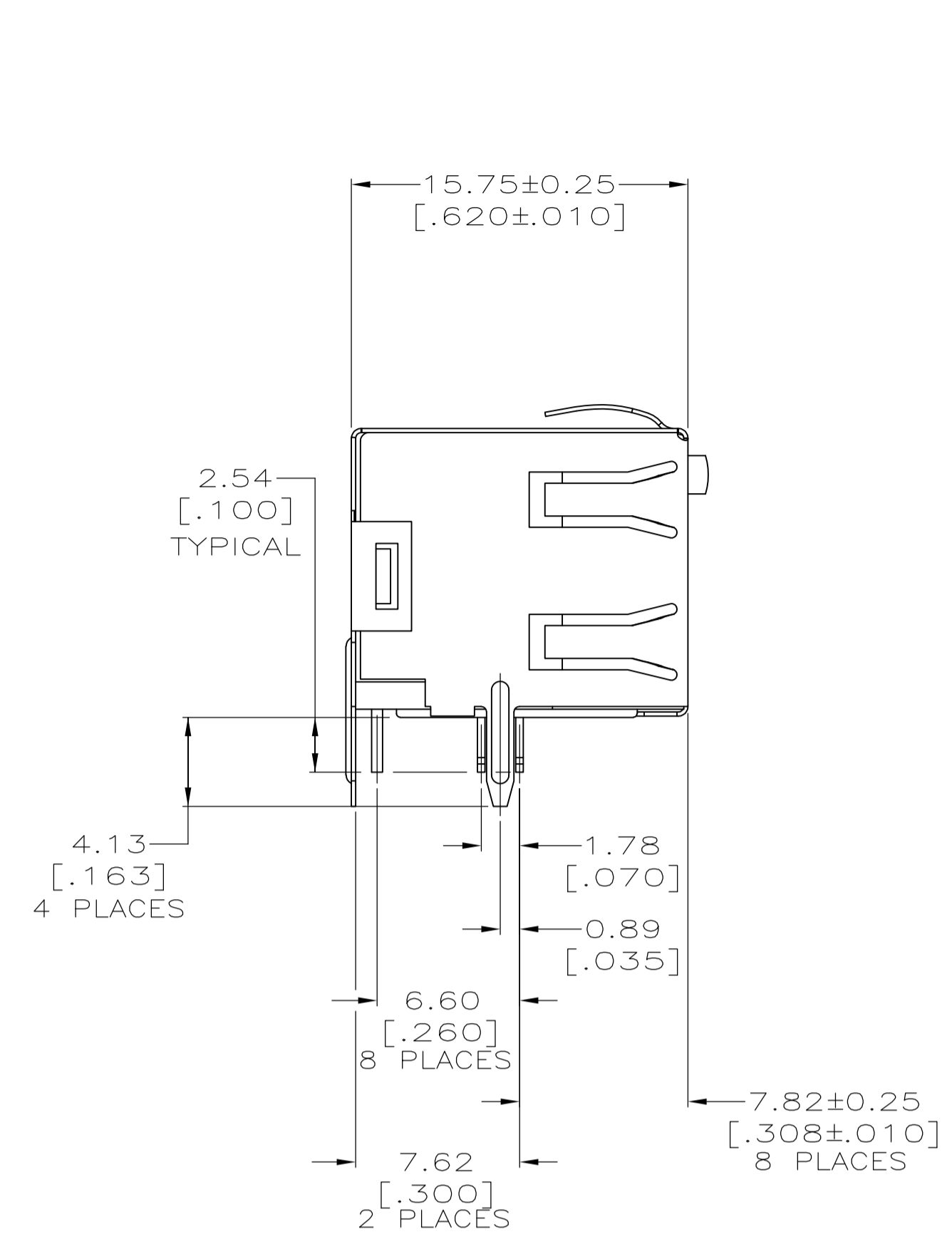
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LOC		DIST		REVISIONS			
AA	22	F	LTR	DESCRIPTION	DATE	DWN	APVD
		A		REV PER EC 0511-0201-04	15JUN2005	LV	SF
		A1		REVISED PER ECO-09-024927	10NOV09	KK	AEG



- MATERIAL:**  
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0.  
 TERMINALS - 0.36[.014] THICK PHOS BRONZE PLATED WITH 3.81µm[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA. 1.27µm [.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm [.000050] MINIMUM THICK NICKEL.  
 SHIELD - 0.196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27µm[.000050] MINIMUM SATIN NICKEL WITH 2.03µm[.000080] MINIMUM HOT TIN DIP ON PCB GROUND TABS.  
 LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.51 x 0.51[.020 x .020] CARBON STEEL WIREFRAME LEADS PREPLATED WITH 8.89 µm[.0003500] THICK Sn/Cu OVER 2.03 µm[.000080] THICK Ag OVER 1.02µm[.000040] THICK Cu OVER 3.56 µm[.000140] THICK Ni OVER 1.02µm[.000040] Cu UNDERPLATE
- JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
  - SUGGESTED PANEL OPENING DIMENSIONS.
  - SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
  - SEE TABLE FOR COLOR OF LEDS AND NUMBER REQUIRED.
  - THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.
  - OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI

SUGGESTED PRINTED CIRCUIT BOARD LAYOUT  
 (COMPONENT SIDE)

INDICATOR COLOR FOR EACH HOUSING	POSITION 2	POSITION 1	PART NUMBER
GREEN	GREEN	GREEN	6364173-5
YELLOW	GREEN	GREEN	-6364173-1

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN L. VARELA - DOCKS 15JUN2005		Tyco Electronics Corporation	
DIMENSIONS: mm [INCHES]		CHK J. WESTMAN 15JUN2005		Harrisburg, Pa 17105-3608	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD S. FLICKINGER 15JUN2005		NAME	
0. PLC ± -	1. PLC ± -	PRODUCT SPEC		INVERTED MODULAR JACK ASSEMBLY, 1X2, PANEL GROUND, SHIELDED, NO MOUNTING LEGS, WITH LEDS	
2. PLC ± 0.25[.01]	3. PLC ± 0.13[.005]	APPLICATION SPEC		108-1163-4	
4. PLC ± -	ANGLES ± -	SIZE		114-2154	
MATERIAL	FINISH	WEIGHT		SCALE	
		CUSTOMER DRAWING		1:1	
		DRAWING NO		SHEET	
		A1 00779		1 OF 1	
		DRAWING NO		REV	
		6364173		A1	